

# NB6N239S

## 3.3 V, 3.0 GHz Any Differential Clock IN to LVDS OUT $\div 1/2/4/8$ , $\div 2/4/8/16$ Clock Divider

The NB6N239S is a high-speed, low skew clock divider with two divider circuits, each having selectable clock divide ratios;  $\div 1/2/4/8$  and  $\div 2/4/8/16$ . Both divider circuits drive LVDS compatible outputs. (More device information on page 7). The NB6N239S is a member of the ECLinPS MAX™ family of high performance clock products.

### Features

- Maximum Clock Input Frequency, 3.0 GHz (1.5 GHz with  $\div 1$ )
- Input Compatibility with LVDS/LVPECL/CML/HSTL
- Rise/Fall Time 120 ps Typical
- < 5 ps Typical Within Device Output Skew
- Example; 622.08 MHz Input Generates 38.88 MHz to 622.08 MHz Outputs
- Internal 50  $\Omega$  Termination Provided
- Random Clock Jitter < 2 ps RMS
- Divide-by-1 Edge of QA Aligned to QB Divided Output
- Operating Range:  $V_{CC} = 3.0\text{ V}$  to  $3.465\text{ V}$  with  $GND = 0\text{ V}$
- Master Reset for Synchronization of Multiple Chips
- $V_{BBAC}$  Reference Output
- Synchronous Output Enable/Disable

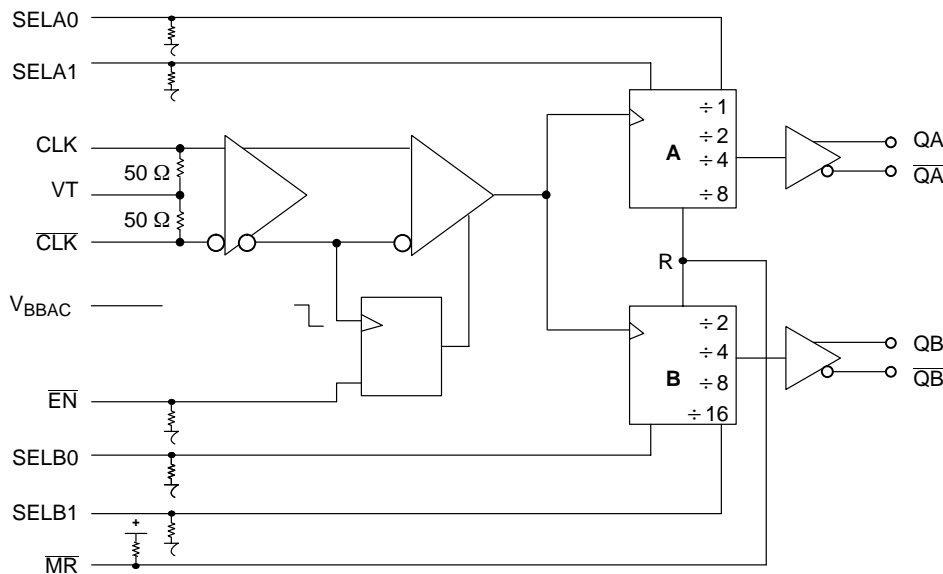


Figure 1. Simplified Logic Diagram



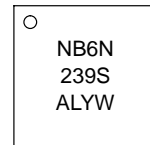
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### MARKING DIAGRAM\*



Bottom View  
QFN-16  
MN SUFFIX  
CASE 485G



A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week

\*For additional marking information, refer to Application Note AND8002/D.

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.

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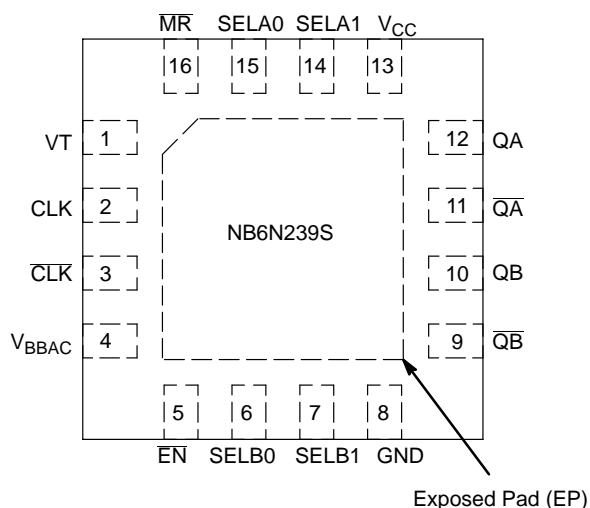


Figure 2. Pinout: QFN-16 (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description
1	VT		Internal 100 $\Omega$ Center-Tapped Termination Pin for CLK and $\overline{\text{CLK}}$ .
2	CLK	LVDS, LVPECL, CML, HSTL Input	Noninverted Differential CLOCK Input.
3	$\overline{\text{CLK}}$	LVDS, LVPECL, CML, HSTL Input	Inverted Differential CLOCK Input.
4	$V_{\text{BBAC}}$		Output Voltage Reference for Capacitor Coupled Inputs, only.
5	$\overline{\text{EN}}^*$	LVC MOS/LVTTL Input	Synchronous Output Enable
6	SELB0*	LVC MOS/LVTTL Input	Clock Divide Select Pin
7	SELB1*	LVC MOS/LVTTL Input	Clock Divide Select Pin
8	GND	Power Supply	Negative Supply Voltage
9	$\overline{\text{QB}}$	LVDS Output	Inverted Differential Output. Typically terminated with 100 $\Omega$ across differential outputs.
10	QB	LVDS Output	Noninverted Differential Output. Typically terminated with 100 $\Omega$ across differential outputs.
11	$\overline{\text{QA}}$	LVDS Output	Inverted Differential Output. Typically terminated with 100 $\Omega$ across differential outputs.
12	QA	LVDS Output	Noninverted Differential Output. Typically terminated with 100 $\Omega$ across differential outputs.
13	$V_{\text{CC}}$	Power Supply	Positive Supply Voltage.
14	SELA1*	LVC MOS/LVTTL Input	Clock Divide Select Pin
15	SELA0*	LVC MOS/LVTTL Input	Clock Divide Select Pin
16	$\overline{\text{MR}}^{**}$	LVC MOS/LVTTL Input	Master Reset Asynchronous, Default Open High, Asserted LOW
	EP	Power Supply (OPT)	The Exposed Pad on the QFN-16 package bottom is thermally connected to the die for improved heat transfer out of package. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to GND on the PC board.

\*Pins will default LOW when left OPEN.

\*\*Pins will default HIGH when left OPEN.

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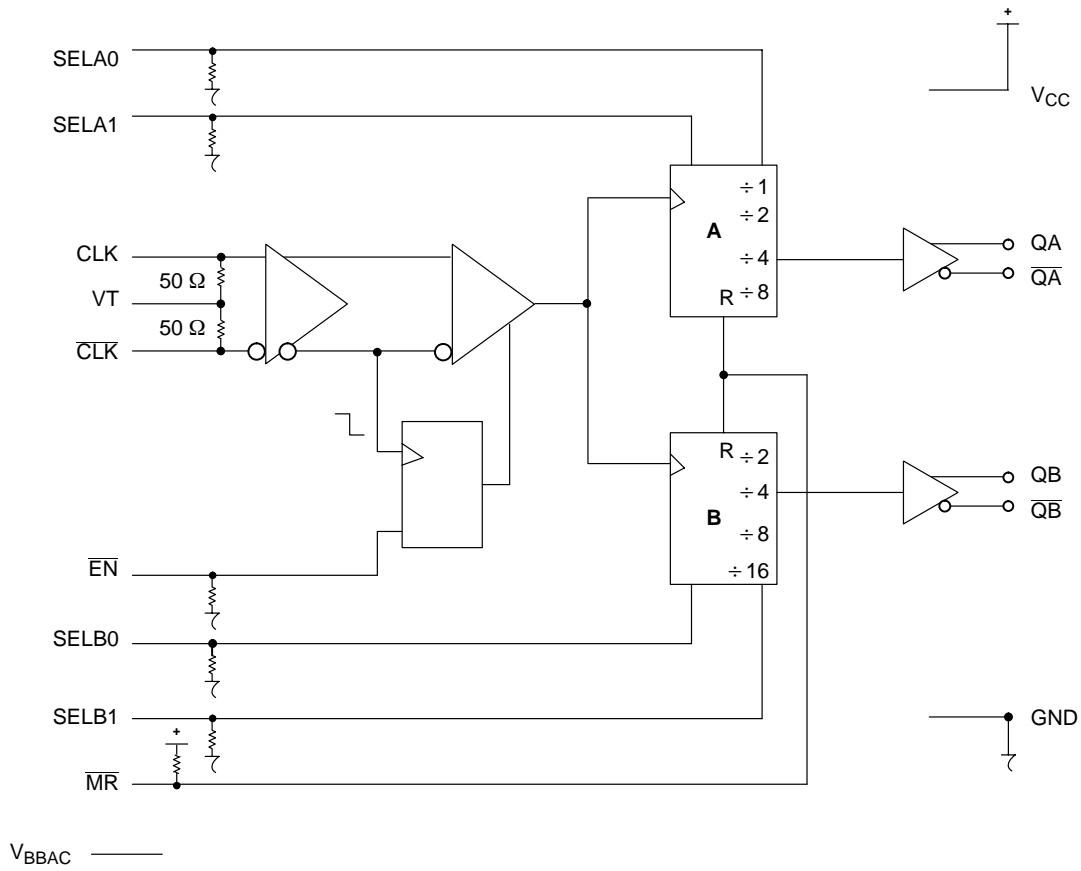


Figure 3. Logic Diagram

Table 2. FUNCTION TABLE

CLK	EN*	MR**	FUNCTION
⌋	L	H	Divide
⌋	H	H	Hold Q
X	X	L	Reset Q

Table 3. CLOCK DIVIDE SELECT, QA OUTPUTS

SELA1*	SELA0*	QA Outputs
L	L	Divide by 1
L	H	Divide by 2
H	L	Divide by 4
H	H	Divide by 8

Table 4. CLOCK DIVIDE SELECT, QB OUTPUTS

SELB1*	SELB0*	QB Outputs
L	L	Divide by 2
L	H	Divide by 4
H	L	Divide by 8
H	H	Divide by 16

⌋ = Low-to-High Transition

⌋ = High-to-Low Transition

X = Don't Care

\*Pins will default LOW when left OPEN.

\*\*Pins will default HIGH when left OPEN.

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**Table 5. ATTRIBUTES**

Characteristics	Value
Internal Input Pulldown Resistor Internal Input Pullup Resistor	75 k $\Omega$ 75 k $\Omega$
ESD Protection Human Body Model Machine Model Charged Device Model	> 1500 V > 150 V > 1000 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	370
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

**Table 6. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Mode Power Supply	GND = 0 V		3.6	V
V <sub>I</sub>	Input Voltage	GND = 0 V	GND $\leq$ V <sub>I</sub> $\leq$ V <sub>CC</sub>	3.6	V
I <sub>SC</sub>	Output Short Circuit Current Line-to-Line Line-to-GND			12 24	mA mA
I <sub>BBAC</sub>	V <sub>BBAC</sub> Sink/Source			$\pm$ 0.5	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	$^{\circ}$ C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	$^{\circ}$ C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm		41.6 35.2	$^{\circ}$ C/W $^{\circ}$ C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board		4.0	$^{\circ}$ C/W
T <sub>sol</sub>	Wave Solder Pb Pb-Free	< 3 sec @ 248 $^{\circ}$ C < 3 sec @ 260 $^{\circ}$ C		265 265	$^{\circ}$ C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

**Table 7. DC CHARACTERISTICS, CLOCK INPUTS, LVDS OUTPUTS**

( $V_{CC} = 3.0\text{ V to }3.465\text{ V}$ ,  $GND = 0\text{ V}$ )

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$I_{CC}$	Power Supply Current (Inputs and Outputs OPEN)				35	45	55				mA
$V_{OH}$	Output HIGH Voltage (Notes 2)			1600			1600			1600	mV
$V_{OL}$	Output LOW Voltage (Notes 2)	900			900			900			mV
$V_{OD}$	Differential Output Voltage (Figure 21)	250		450	250		450	250		450	mV
$\Delta V_{OD}$	$V_{OD}$ Magnitude Change	0		50	0		50	0		50	mV
$V_{OS}$	Offset Voltage (Figure 21)	1125		1375	1125		1375	1125		1375	mV
$\Delta V_{OS}$	$V_{OS}$ Magnitude Change	0		50	0		50	0		50	mV

**DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED** (Figures 7, 10)

$V_{th}$	Input Threshold Reference Voltage (Note 3)	100		$V_{CC} - 100$	100		$V_{CC} - 100$	100		$V_{CC} - 100$	mV
$V_{IH}$	Single-ended Input HIGH Voltage	$V_{th} + 100$		$V_{CC}$	$V_{th} + 100$		$V_{CC}$	$V_{th} + 100$		$V_{CC}$	mV
$V_{IL}$	Single-ended Input LOW Voltage	GND		$V_{th} - 100$	GND		$V_{th} - 100$	GND		$V_{th} - 100$	mV
$V_{BBAC}$	Output Voltage Reference @ 100 $\mu\text{A}$ (Note 6) $V_{CC} = 3.3\text{ V}$ $V_{CC} = 2.5\text{ V}$	$V_{CC} - 1460$ 1840 1040	$V_{CC} - 1330$ 1970 1170	$V_{CC} - 1200$ 2100 1300	$V_{CC} - 1460$ 1840 1040	$V_{CC} - 1340$ 1960 1160	$V_{CC} - 1200$ 2100 1300	$V_{CC} - 1460$ 1840 1040	$V_{CC} - 1350$ 1950 1150	$V_{CC} - 1200$ 2100 1300	mV

**DIFFERENTIAL INPUT DRIVEN DIFFERENTIALLY** (Figures 8, 9, 11) (Note 5)

$V_{IHD}$	Differential Input HIGH Voltage	100		$V_{CC}$	100		$V_{CC}$	100		$V_{CC}$	mV
$V_{ILD}$	Differential Input LOW Voltage	GND		$V_{CC} - 100$	GND		$V_{CC} - 100$	GND		$V_{CC} - 100$	mV
$V_{CMR}$	Input Common Mode Range (Differential Cross-point Voltage) (Note 4)	50		$V_{CC} - 50$	50		$V_{CC} - 50$	50		$V_{CC} - 50$	mV
$V_{ID}$	Differential Input Voltage ( $V_{IHD(CLK)}$ - $V_{ILD(CLK)}$ ) and ( $V_{IHD(CLK)}$ - $V_{ILD(CLK)}$ )	100		$V_{CC} - GND$	100		$V_{CC} - GND$	100		$V_{CC} - GND$	mV
$R_{TIN}$	Internal Input Termination Resistor	45	50	55	45	50	55	45	50	55	$\Omega$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- Outputs loaded with 100  $\Omega$  across LVDS outputs.
- $V_{th}$  is applied to the complementary input when operating in single-ended mode.
- $V_{CMR_{MIN}}$  varies 1:1 with GND,  $V_{CMR_{MAX}}$  varies 1:1 with  $V_{CC}$ .
- Input and output voltage swing is a single-ended measurement operating in differential mode.
- $V_{BBAC}$  used to rebias capacitor-coupled inputs only (see Figures 16 and 17).

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**Table 8. DC CHARACTERISTICS, LVTTTL/LVCMOS INPUTS** ( $V_{CC} = 3.0\text{ V to }3.465\text{ V}$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C to }+85^\circ\text{C}$ )

Symbol	Characteristic	Min	Typ	Max	Unit
$V_{IH}$	Input HIGH Voltage (LVCMOS/LVTTTL)	2.0		$V_{CC}$	V
$V_{IL}$	Input LOW Voltage (LVCMOS/LVTTTL)	GND		0.8	V
$I_{IH}$	Input HIGH Current	-150		150	$\mu\text{A}$
$I_{IL}$	Input LOW Current	-150		150	$\mu\text{A}$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

**Table 9. AC CHARACTERISTICS**  $V_{CC} = 2.375\text{ V to }3.465\text{ V}$ ;  $GND = 0\text{ V}$  (Note 7)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{in}$	Maximum Input CLOCK Frequency QA/QB = ( $\div 2$ , $\div 4$ , $\div 8$ , $\div 16$ ) QA = ( $\div 1$ )			3.0 1.5			3.0 1.5			3.0 1.5	GHz
$V_{OUTPP}$	Output Voltage Amplitude (Notes 9, 10) QA ( $\div 2$ , 4, 8), QB ( $\div n$ ) QA ( $\div 1$ ), QB ( $\div n$ )	200 200	350 350	450 450	200 200	350 350	450 450	200 200	350 350	450 450	mV
$t_{PLH}$ , $t_{PHL}$	Propagation Delay to Output Differential @ 50 MHz	550 420		780 660	550 420		780 660	550 420		780 660	ps
$t_{RR}$	Reset Recovery	0	-90		0	-90		0	-90		ps
$t_s$	Setup Time @ 50 MHz	0 0	-60 -300		0 0	-60 -300		0 0	-60 -300		ps
$t_h$	Hold Time @ 50 MHz	150 700	65 200		150 700	65 200		150 700	65 200		ps
$t_{skew}$	Within-Device Skew @ 50 MHz Device-to-Device Skew Duty Cycle Skew		5 25 25	30 80 40		5 30 30	30 90 45		6 30 30	35 90 45	ps
$t_{PW}$	Minimum Pulse Width	550			550			550			ps
$t_{JITTER}$	RMS Random Clock Jitter			2			2			2	ps
$V_{INPP}$	Input Voltage Swing (Differential Configuration) (Note 9)	100		$V_{CC}$ -GND	100		$V_{CC}$ -GND	100		$V_{CC}$ -GND	mV
$t_r$ $t_f$	Output Rise/Fall Times @ 50 MHz (20% - 80%)	70	120	190	70	120	190	70	120	190	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

7. Measured using a 750 mV, 50% duty cycle clock source. All loading with 100  $\Omega$  across LVDS outputs.
8. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.
9. Input and output voltage swing is a single-ended measurement operating in differential mode.
10. Output Voltage Amplitude ( $V_{OHCLK} - V_{OLCLK}$ ) at input CLOCK frequency,  $f_{in}$ . The output frequency,  $f_{out}$ , is the input CLOCK frequency divided by  $n$ ,  $f_{out} = f_{in} \div n$ . Input CLOCK frequency is  $\leq 3.0\text{ GHz}$ .

Application Information

The NB6N239S is a high-speed, low skew clock divider with two divider circuits, each having selectable clock divide ratios;  $\div 1/2/4/8$  and  $\div 2/4/8/16$ . Both divider circuits drive differential LVDS compatible outputs. The internal dividers are synchronous to each other. Therefore, the common output edges are precisely aligned.

The NB6N239S clock inputs can be driven by a variety of differential signal level technologies including LVDS, LVPECL, HSTL, or CML. The differential clock input buffer employs a pair of internal 50  $\Omega$  termination resistors in a 100  $\Omega$  center-tapped configuration and accessible via the VT pin. This feature provides transmission line termination on-chip, at the receiver end, eliminating external components. The  $V_{BBAC}$  reference output is recommended to be used to rebias differential or

single-ended input capacitor-coupled CLOCK signals. For the capacitor-coupled CLK and/or  $\overline{CLK}$  inputs,  $V_{BBAC}$  should be connected to the  $V_T$  pin and bypassed to ground with a 0.01  $\mu F$  capacitor. Inputs CLK and  $\overline{CLK}$  must be signal driven or auto oscillation may result.

The common enable ( $\overline{EN}$ ) is synchronous so that the internal divider flip-flops will only be enabled/disabled when the internal clock is in the LOW state. This avoids any chance of generating a runt pulse on the internal clock when the device is enabled/disabled, as can happen with an asynchronous control. The internal enable flip-flop is clocked on the falling edge of the input clock. Therefore, all associated specification limits are referenced to the negative edge of the clock input.

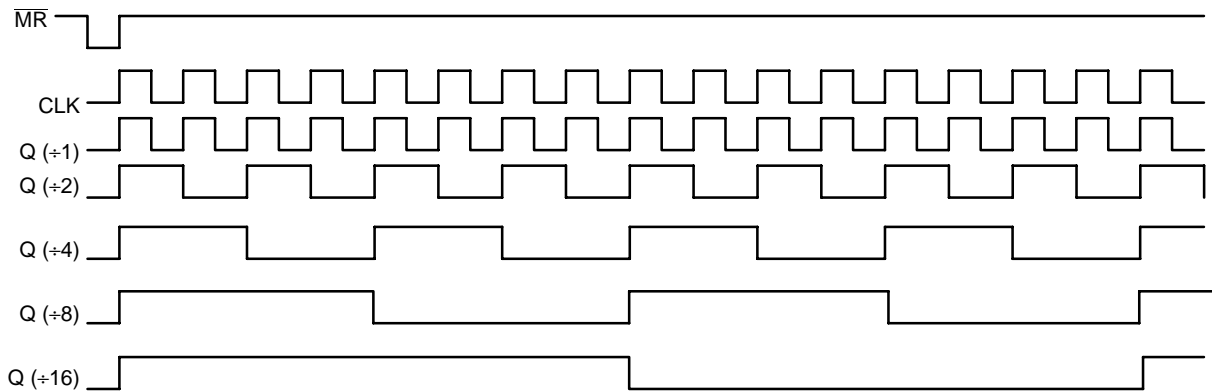
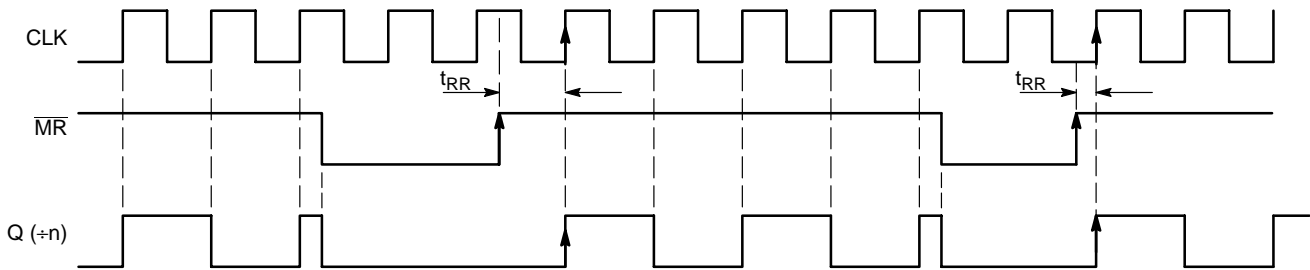


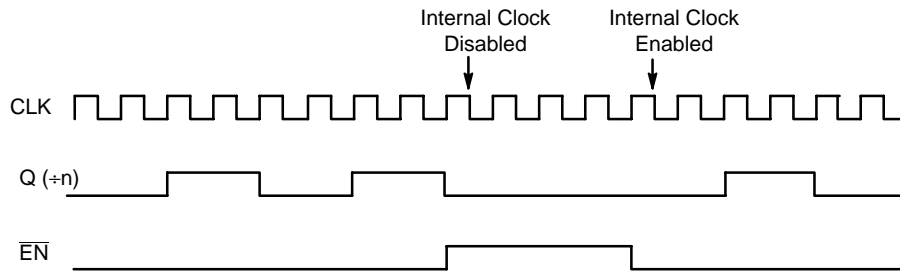
Figure 4. Timing Diagram



NOTE: On the rising edge of  $\overline{MR}$ , Q goes HIGH after the first rising edge of CLK.

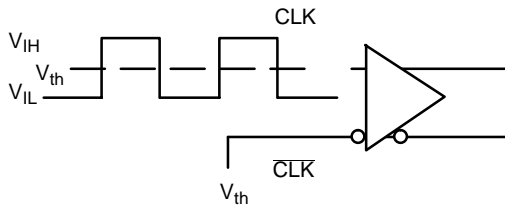
Figure 5. Master Reset Timing Diagram

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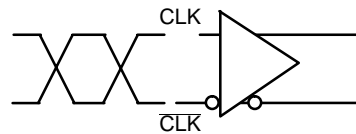


**Figure 6. Output Enable Timing Diagrams**

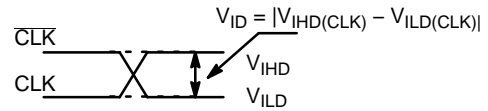
The  $\overline{EN}$  signal will “freeze” the internal divider flip–flops on the first falling edge of CLK after its assertion. The internal divider flip–flops will maintain their state during the freeze. When  $\overline{EN}$  is deasserted (LOW), and after the next falling edge of CLK, then the internal divider flip–flops will “unfreeze” and continue to their next state count with proper phase relationships.



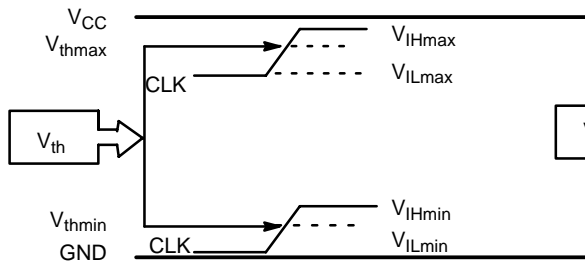
**Figure 7. Differential Input Driven Single-Ended**



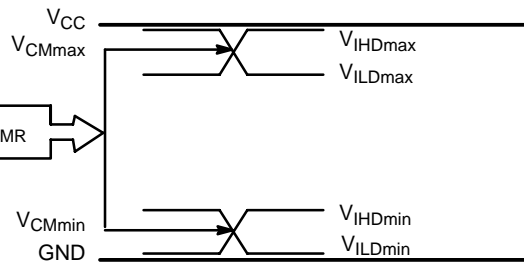
**Figure 8. Differential Inputs Driven Differentially**



**Figure 9. Differential Inputs Driven Differentially**



**Figure 10.  $V_{Th}$  Diagram**



**Figure 11.  $V_{CMR}$  Diagram**



# NB6N239S

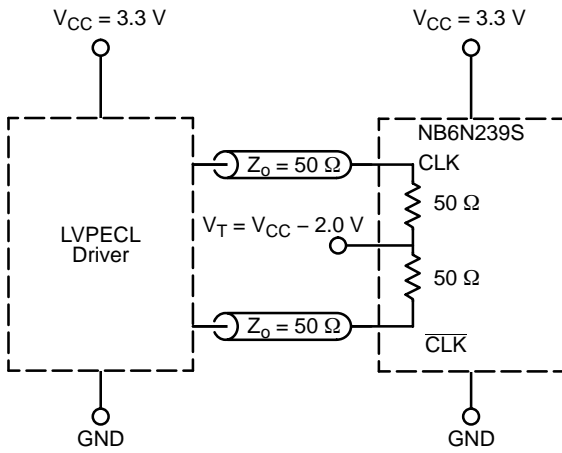


Figure 12. LVPECL Interface

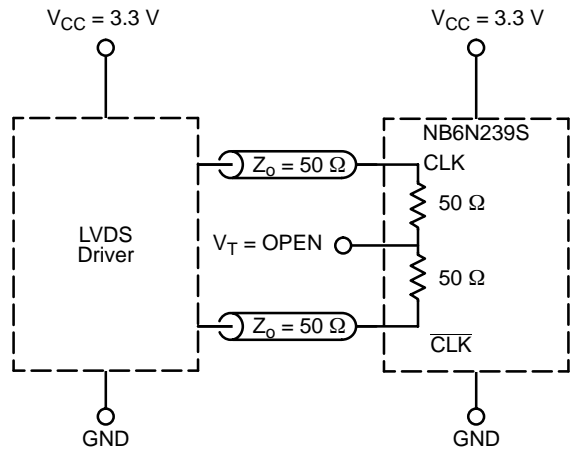


Figure 13. LVDS Interface

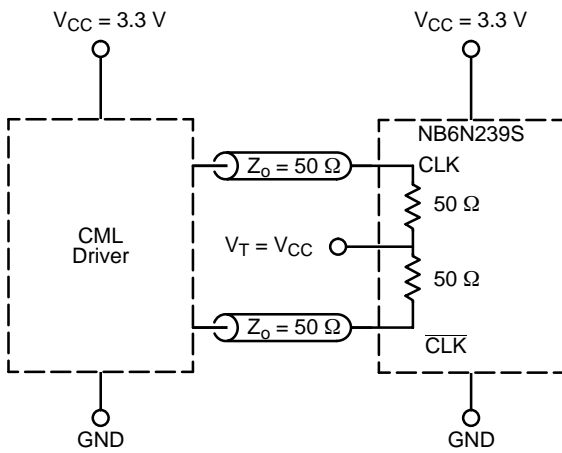


Figure 14. Standard 50 Ω Load CML Interface

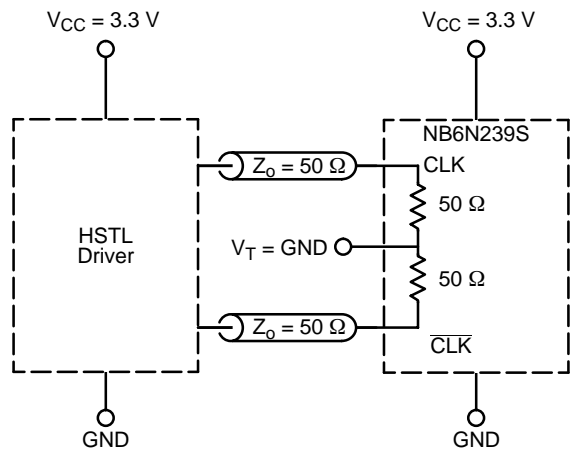


Figure 15. Standard 50 Ω Load HSTL Interface

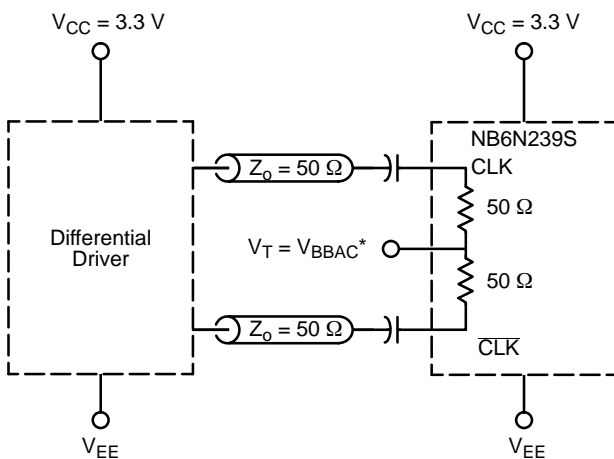


Figure 16. Capacitor-Coupled Differential Interface ( $V_T$  Connected to  $V_{BBAC}$ )

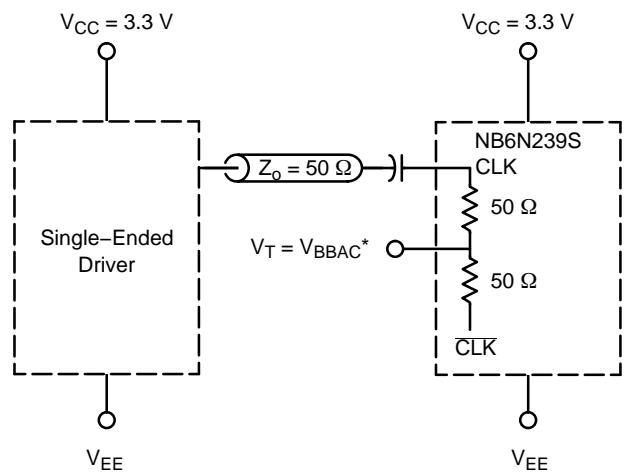
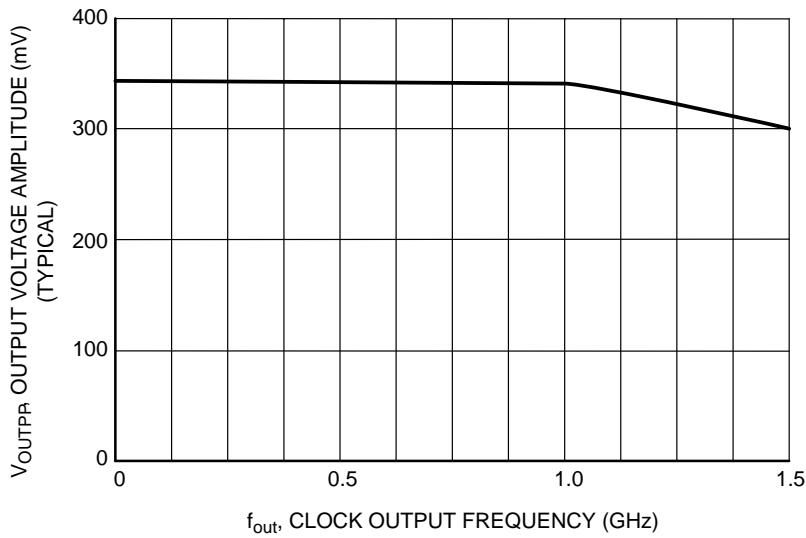


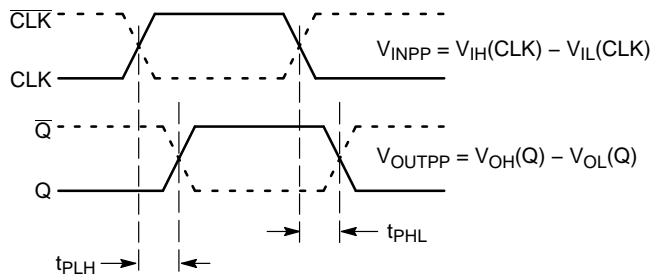
Figure 17. Capacitor-Coupled Single-Ended Interface ( $V_T$  Connected to  $V_{BBAC}$ )

\* $V_{BBAC}$  bypassed to ground with a 0.01  $\mu$ F capacitor.

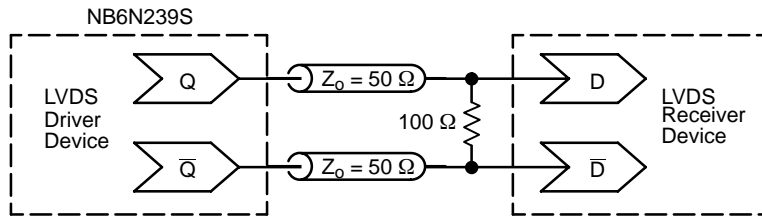
# NB6N239S



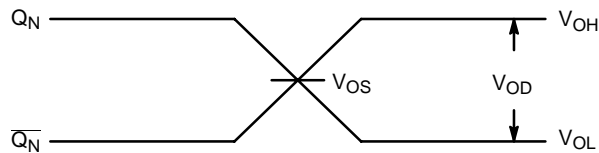
**Figure 18. Output Voltage Amplitude (V<sub>OUTPP</sub>) versus Output Clock Frequency at 25°C (Typical) (f<sub>out</sub> (QA/QB) = f<sub>in</sub> ÷ n; f<sub>in</sub> ≤ 3.0 GHz).**



**Figure 19. AC Reference Measurement**



**Figure 20. Typical LVDS Termination for Output Driver and Device Evaluation, If Receiver Has On-chip Termination, 100 Ω Resistor is Not Needed**



**Figure 21. LVDS Output**

# NB6N239S

## ORDERING INFORMATION

Device	Package	Shipping†
NB6N239SMN	QFN-16, 3 x 3 mm	123 Units / Rail
NB6N239SMNG	QFN-16, 3 x 3 mm (Pb-Free)	123 Units / Rail
NB6N239SMNR2	QFN-16, 3 x 3 mm	3000 / Tape & Reel
NB6N239SMNR2G	QFN-16, 3 x 3 mm (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

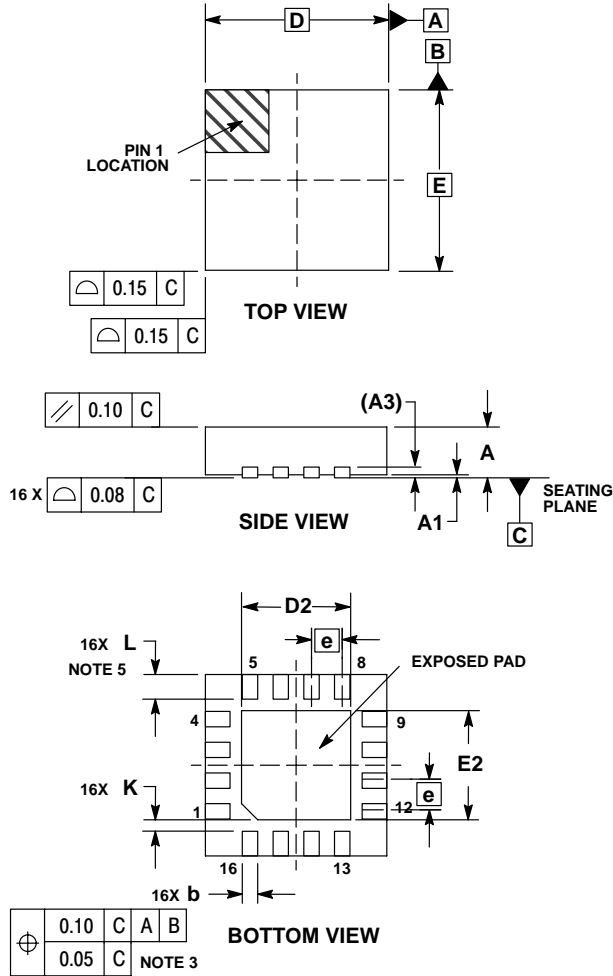
### Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPiCE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

# NB6N239S

## PACKAGE DIMENSIONS

QFN-16  
CASE 485G-01  
ISSUE B




### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5.  $L_{max}$  CONDITION CAN NOT VIOLATE 0.2 MM MINIMUM SPACING BETWEEN LEAD TIP AND FLAG

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	3.00	BSC
D2	1.65	1.85
E	3.00	BSC
E2	1.65	1.85
e	0.50	BSC
K	0.20	---
L	0.30	0.50

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